

## ABSTRACT

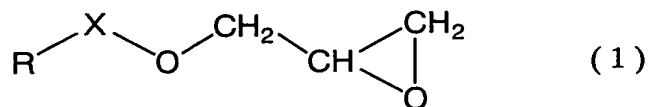
The present invention provides a thermosetting resin composition containing the following (A) component and (B) component, an adhesive containing the thermosetting resin composition and an organic solvent and/or water, and an adhesive film containing the thermosetting resin composition.

(A) component: at least one kind of phenol resin selected from the group consisting of alkylphenol novolak, a phenol adduct of an aliphatic polymer containing a double bond, and a phenol adduct of an alicyclic polymer containing a double bond

(B) component: epoxy group - containing ethylene-based copolymer obtained by polymerizing the following (b<sub>1</sub>) and (b<sub>2</sub>):

(b<sub>1</sub>) ethylene and/or propylene

(b<sub>2</sub>) monomer represented by the following formula (1):



(wherein R represents a hydrocarbon group of a carbon number of 2 to 18 having a double bond, wherein at least one of hydrogen atoms of the hydrocarbon group may be substituted with a halogen atom, a hydroxyl group or a carboxyl group, and X represents a single bond or a carbonyl group).